

IN THE SPECIFICATION:

Pursuant to 37 C.F.R. 1.121, the following are clean copies of the replacement paragraphs indicated. Marked-up versions of the paragraphs are attached as a separate sheet.

Please delete the third full paragraph on page 31 of the specification and replace it with the following substitute paragraph:

C1 In the present invention, the resin sheet is preferably a sheet formed from an insulating resin, and the resin sheet is more preferably a sheet formed from at least one insulating resin selected from the group consisting of polyimide, polyester, polypropylene, polyphenylene sulfide, polyvinylidene chloride, EVAL, an ethylene-vinyl alcohol copolymer available from Kurary Co., LTD., Osaka, Japan, glass epoxy and a BT resin.

Please delete the first full paragraph on page 41 of the specification and replace it with the following substitute paragraph:

C2 The resin sheet 18 employable herein is a sheet of polyimide, polyester, polypropylene, polyphenylene sulfide, polyvinylidene chloride, EVAL, an ethylene-vinyl alcohol copolymer available from Kurary Co., LTD., Osaka, Japan, glass epoxy, a BT resin or the like.

IN THE CLAIMS:

Please cancel claims 119 and 135.

Please cancel the previous versions of claims 116, 120, and 136, and rewrite them as follows. Pursuant to 37 C.F.R. 1.121, the following are clean copies of the rewritten claims. Marked-up versions of claims 116, 120, and 136 are attached as a separate sheet.

C3 116. (Once Amended) A printed wiring board-forming sheet comprising an insulating resin sheet having a through hole inserted and filled with a

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